

Chinese and English Definitions of Acronyms Related to Ethernet Products

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ABSTRACT

The Chinese and English Definitions of Acronyms Related to Ethernet Products application report is intended to provide standardized definitions for commonly used acronyms in both Chinese and English.

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1 Introduction

This application report is intended to provide a standardized acronym reference for both Chinese and English users. [Table 1](#) is sorted alphabetically for ease of search and reference.

2 Acronyms and Definitions

Table 1. Acronyms Definitions

Acronym (缩写)	English Definition (英文注释)	Chinese Definition (中文注释)
ADC	Analog to Digital Converter	模拟/数字转换器
AEQ	Adaptive Equalizer	自适应均衡器
ALCD	Active Link Cable Diagnostics	动态链路电缆诊断
AVB	Audio Video Bridging	音频视频桥接
AVD	Analog Voltage Supply	模拟电源
BMC	Best Master Clock	最佳主时钟算法
CAT5	Category-5 Cable	第五类双绞线
CDM	Charged-Device Model	充电器件模型
CMC	Common Mode Choke	共模电感线圈
CML	Current Mode Line Driver	电流驱动器
COL	Collision Detect	冲突监测
CRC	Cyclic Redundancy Check	循环冗余检查
CRS	Carrier Sense	载波侦听
CRS_DV	Carrier Sense / Receive Data Valid	载波侦听 / 接收数据有效信号
CSMA/CD	Carrier Sense Multiple Access with Collision Detection	载波监听多路访问技术
CT	Center Tap Supply Rail	中点抽头电源
DAC	Digital to Analog Converter	数字/模拟转换器
DDR	Double Data Rate	双倍数据速率
DEST	Destination Address	终点地址
DEVAD	Device Address	装置地址
DUT	Device Under Test	被测试元件

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Table 1. Acronyms Definitions (continued)

Acronym (缩写)	English Definition (英文注释)	Chinese Definition (中文注释)
EEE	Energy Efficient Ethernet	节能以太网
EMC	Electromagnetic Compatibility	电磁兼容
EMI	Electromagnetic Interference	电磁干扰
EMS	Electromagnetic Susceptibility	电磁屏蔽
ESD	Electrostatic Discharge	静电放电
EVM	Evaluation Module	评估模块
FLP	Fast Link Pulse	快速链路脉冲
FX	Fiber	光纤
GMII	Gigabit Media Independent Interface	千兆媒体独立接口
GND	Ground	接地端
GPIO	General Purpose Input/Output	通用输入输出口
HBM	Human Body Model	人体模型
ID	Internal Delay	内部延迟
IEC	International Electrotechnical Commission	国际电工委员会
IEEE	Institute of Electrical and Electronics Engineers	电气和电子工程师协会
IPG	Inter-Packet Gap	数据包间隔
JTAG	Joint Test Action Group	联合测试工作组
LP	Link Partner	链接对象
LPI	Low-Power Idle	低功耗闲置
MAC	Media Access Controller	介质访问控制器
MDC	Management Data Clock	管理数据时钟
MDI	Media Dependent Interface	介质有关接口
MDIO	Management Data I/O	管理数据输入输出口
MDIX	Media Dependent Interface Crossover	介质有关交叉接口
MII	Media Independent Interface	媒介独立接口
MLT-3	3 level Multi Level Transitions	多电平传输-3
MM	Machine Model	机器模型
NLP	Normal Link Pulse	正常链路脉冲
Opcode	Operation Code	操作代码
PAM	Pulse Amplitude Modulation	脉冲振幅调变
PCS	Physical Coding Sublayer	物理编码子层
PD	Pull-Down	下拉
PHY	Physical Layer	物理层
PHYAD	Physical Layer Address	物理层地址
PLL	Phase Lock Loop	锁相环
PMA	Physical Medium Attachment Sublayer	物理媒介连接子层
PMD	Physical Medium Dependent Sublayer	物理介质相关子层
PoE	Power over Ethernet	以太网供电
PTP	Precision Time Protocol	精确时钟同步协议
PU	Pull-Up	上拉
QFN	Quad Flat No-leads package	方形扁平无引脚封装
QFP	Quad Flat Package	方形扁平式封装
RBIAS	Bias Resistor	偏置电阻器连接
RD	Differential Receive Input	差分信号输入
RGMII	Reduced Gigabit Media Independent Interface	简化千兆媒介独立接口
RMII	Reduced Media Independent Interface	简化媒介独立接口
RX	Receive	接收

Table 1. Acronyms Definitions (continued)

Acronym (缩写)	English Definition (英文注释)	Chinese Definition (中文注释)
RX_CLK	Receive Clock	接收时钟信号
RX_CTRL	Receive Control	接收启动和数据错误信号
RX_D	Receive Data	接收数据
RX_DV	Receive Data Valid	接收数据有效信号
RX_ER	Receive Error	接收数据错误信号
SFD	Start Frame Delimiter	起始帧分界符
SFF	Small Form Factor	小封装技术
SFP	Small Form-Factor Pluggable (Fiber Transceiver)	小封装可插拔收发器
SGMII	Serial Gigabit Media Independent Interface	串行千兆媒介独立接口
SMI	Serial Management Interface	串行管理接口
SNI	Serial Network Interface	串行网络接口
SOC	System on Chip	系统级芯片
SRC	Source Address	源头地址
STP	Shielded Twisted Pair	屏蔽双绞线
TD	Differential Transmit Output	发送差分信号
TDR	Time Domain Reflectometry	时域反射技术
TSN	Time Sensitive Networking	时效性网络
TX	Transmit	发送
TX_CLK	Transmit Clock	发送时钟信号
TX_CTRL	Transmit Control	发送启动和数据错误信号
TX_D	Transmit Data	发送数据
TX_EN	Transmit Enable	发送启用信号
TX_ER	Transmit Error	发送数据错误信号
UTP	Unshielded Twisted Pair	非屏蔽双绞线
VDDIO	I/O Voltage Supply	输入输出电源
VML	voltage mode line driver	电压驱动器
WoL	Wake-on-LAN	远程唤醒技术
WQFN	Thin Quad Flat No-lead	极细方形扁平无引脚封装
XI	Crystal/Oscillator Input	晶振/振荡器输入
XO	Crystal output	晶振输出

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